

Form PTO-1595 (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) Tab settings ▼ ▼ ▼ ▼ ▼ ▼ ▼		RECORDATION FORM COVER SHEET PATENTS ONLY		U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.					
1. Name of conveying party(ies): KAC Holdings, Inc. d/b/a Kester, Inc. Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			2. Name and address of receiving party(ies) Name: <u>CIT Lending Services Corporation</u> Internal Address: _____ <u>c/o CIT Group Inc.</u> <u>Business Credit/Corporate Finance Group</u> Street Address: <u>1 CIT Drive, 3rd Floor</u> _____ City: <u>Livingston</u> State: <u>NJ</u> Zip: <u>07039</u> Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____ Execution Date: <u>December 10, 2004</u>			4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: _____ A. Patent Application No.(s) <u>6,819,004</u> B. Patent No.(s) <u>361,671</u> Additional numbers attached? <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		
5. Name and address of party to whom correspondence concerning document should be mailed: Name: _____ Internal Address: _____ _____ _____ Street: <u>Attn: Penelope J.A. Agodoa</u> <u>Federal Research Company, LLC</u> <u>1030 15th Street, NW, Suite 920</u> <u>Washington, DC 20005</u> City: <u>202.783.2700</u>			6. Total number of applications and patents involved: <u>12</u> 7. Total fee (37 CFR 3.41).....\$ <u>480.00</u> <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account 8. Deposit account number: <u>50-3155</u> (Attach duplicate copy of this page if paying by deposit account)		
DO NOT USE THIS SPACE					
9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i> <div style="display: flex; justify-content: space-between;"> <div style="width: 30%;"> <u>Joyce Francis</u> Name of Person Signing </div> <div style="width: 30%; text-align: center;"> Signature </div> <div style="width: 30%; text-align: right;"> <u>02/07/05</u> Date </div> </div> <div style="text-align: right; margin-top: 10px;"> Total number of pages including cover sheet, attachments, and documents: <u>2</u> </div>					

Mail documents to be recorded with required cover sheet information to:
 Commissioner of Patents & Trademarks, Box Assignments
 Washington, D.C. 20231

CH \$480.00 503155 09361671

Schedule 1

KAC HOLDINGS, INC

PATENTS AND PATENT APPLICATIONS

Title	Country	Patent No. Issue Date	App. No / Filing Date
Encapsulant with fluxing properties and method of use in flip-chip surface mount reflow soldering	U.S.		361,671 2/10/03
Encapsulant with fluxing properties and method of use in flip-chip surface mount reflow soldering	U.S.	6,819,004 11/16/04	361,390 2/10/03
Encapsulant with fluxing properties and method of use	U.S.		08/644,912 5/28/96
Encapsulant with fluxing properties and method of use in flip-chip surface mount reflow soldering	U.S.		PCT/US96/12759 8/9/96
Method of Controlling Solder Deposition Utilizing Two Fluxes and Preform	U.S.	6,786,391 9/7/04	10/271,883 10/16/02
Surface Reactive Preservative for use with Solder Preforms	U.S.		10/682,699 10/09/03
Method of manufacturing an electrical connection using solder flux compatible with flip chip underfill material	U.S.	6,615,484 9/9/03	051,661 1/18/02
Solder flux compatible with flip-chip underfill material	U.S.	6,367,150 4/9/02	148,506 9/4/98
No-clean, low-residue, volatile organic compound free soldering flux and method of use	U.S.	5,334,260 8/2/94	014,201 2/5/93
No-clean, low-residue, volatile organic compound free soldering flux and method of use	U.S.	5,281,281 1/25/94	014,203 2/5/93
Package for spooled products	U.S.	5,064,066 11/12/91	674,180 3/25/91
Method of controlling solder deposition utilizing two fluxes and perform	U.S.		10/934,152 9/3/04

PATENT SECURITY AGREEMENT

WHEREAS, KAC Holdings, Inc., d/b/a Kester, Inc., a Delaware corporation (herein referred to as "Grantor"), owns the letters patent, and/or applications for letters patent, of the United States, more particularly described on Schedule 1 annexed hereto as part hereof (the "Patents");

WHEREAS, Grantor is obligated to CIT Lending Services Corporation, a Delaware corporation, as administrative agent (referred to herein as the "Grantee") and the other Secured Parties as defined in the Omnibus Pledge and Security Agreement dated as of December 10, 2004 (the "Security Agreement") among Grantor, the other Pledgors named therein and the Grantee for the payment and performance of the Secured Obligations (as defined in the Security Agreement); and

WHEREAS, pursuant to the Security Agreement, Grantor has granted to Grantee a security interest in all right, title and interest of Grantor in and to the Patents, together with any reissue, continuation, continuation-in-part or extension thereof, and all proceeds thereof, including, without limitation, any and all causes of action which may exist by reason of infringement thereof for the full term of the Patents (the "Collateral"), to secure the prompt payment and performance of the Secured Obligations;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, Grantor does hereby further grant to Grantee a security interest in the Collateral to secure the prompt payment and performance of the Secured Obligations.

Grantor does hereby further acknowledge and affirm that the rights and remedies of Grantee with respect to the security interest in the Collateral made and granted hereby are more fully set forth in the Security Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein.

Grantee's address is c/o CIT Group Inc., Business Credit/Corporate Finance Group, 1 CIT Drive, 3rd Floor, Livingston, New Jersey 07039.

IN WITNESS WHEREOF, Grantor has caused this Patent Security Agreement to be duly executed by its officer thereunto duly authorized as of the 10 day of December, 2004.

KAC HOLDINGS, INC.

By: _____

Name: Mark Holroyd
Title: VP & Secretary

Patent Security Agreement Signature Page

30986273.WPD

PATENT
REEL: 015740 FRAME: 0817

STATE OF Illinois)
 : ss.:
COUNTY OF Cook)

On this 10 day of December, 2004, before me personally appeared Mark Holroyd, to me known, who, being by me duly sworn, did depose and say that he resides at 718 W. Melrose #4W Chicago, IL 60657 and that he is VP & Secretary of KAC Holdings, Inc., a Delaware corporation described in and which executed the foregoing instrument; and that he is authorized on behalf of KAC Holdings, Inc. to sign his name to the foregoing instrument.

Tara Peterson

Notary Public



30986273.WPD